

Title (en)

Application device for applying a fluid onto a substrate with valve devices, method for cleaning the application device and valve device for application device

Title (de)

Auftragungseinrichtung zum Auftragen von Fluid auf ein Substrat mit Ventileinrichtungen, Verfahren zum Reinigen der Auftragungseinrichtung und Ventileinrichtung für die Auftragungseinrichtung

Title (fr)

Dispositif d'application doté de buses, destiné à appliquer un liquide sur un substrat, procédé destiné à nettoyer le dispositif d'application et les buses du dispositif d'application.

Publication

EP 2002898 A8 20090225 (DE)

Application

EP 07090124 A 20070614

Priority

EP 07090124 A 20070614

Abstract (en)

[origin: EP2002898A1] Application device comprises a cleaning valve arrangement (20) assigned to the fluid inlet channel (110) of a distribution fluid chamber with a cleaning valve nozzle (30) and a valve actuating unit (5) for closing and opening the cleaning valve nozzle. A flow path (100) for cleaning the fluid chamber is formed in the distribution fluid chamber between the fluid inlet channel and the cleaning valve arrangement when the cleaning valve nozzle is open. Independent claims are also included for the following: (1) Method for cleaning the application device; and (2) Electronic control device for the application device. Preferred Features:.

IPC 8 full level

B05B 15/02 (2006.01); **B05B 1/20** (2006.01); **B05B 15/55** (2018.01); **B05C 5/02** (2006.01)

CPC (source: EP KR US)

B05B 1/20 (2013.01 - KR); **B05B 1/3053** (2013.01 - EP KR US); **B05B 15/55** (2018.01 - EP KR US); **B05C 5/0225** (2013.01 - EP KR US); **B05C 5/0279** (2013.01 - EP KR US); **B05B 1/20** (2013.01 - EP US)

Cited by

EP2392408A1; EP3702045A1; US11944990B2; US11167302B2; US11338312B2; WO2018108577A1; WO2018108571A1; US11167297B2; US11167308B2; US11440035B2; US11203030B2; US11813630B2; US11975345B2; US11298717B2; US11504735B2; US11878317B2; EP3424707A1; WO2019007898A1; US11154892B2; EP2801409B1

Designated contracting state (EPC)

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Designated extension state (EPC)

AL BA HR MK RS

DOCDB simple family (publication)

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DOCDB simple family (application)

EP 07090124 A 20070614; AT 08758719 T 20080520; CA 2690062 A 20080520; CA 2690108 A 20080520; CN 200880020045 A 20080520; CN 200880020135 A 20080520; EP 08758718 A 20080520; EP 08758719 A 20080520; EP 2008004122 W 20080520; EP 2008004123 W 20080520; IL 20242609 A 20091201; IL 20242709 A 20091201; JP 2010511513 A 20080520; JP 2010511514 A 20080520; KR 20107000762 A 20080520; KR 20107000763 A 20080520; US 66443908 A 20080520; US 66445008 A 20080520